

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6138322

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MENG YAN	04/16/2020
RECEIVING PARTY DATA	
Name:	YANGTZE MEMORY TECHNOLOGIES CO., LTD.
Street Address:	18 GAOXIN 4TH ROAD, EAST LAKE HIGH-TECH DEVELOPMENT ZONE
City:	WUHAN
State/Country:	CHINA
Postal Code:	430000
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16892993
CORRESPONDENCE DATA	
Fax Number:	(703)935-1394
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7034305759
Email:	uspto@anovalaw.com
Correspondent Name:	ANOVA LAW GROUP, PLLC C/O YMTC
Address Line 1:	21495 RIDGETOP CIRCLE, SUITE 300
Address Line 4:	STERLING, VIRGINIA 20166
ATTORNEY DOCKET NUMBER:	00283.0008.00US
NAME OF SUBMITTER:	TING XUE
SIGNATURE:	/Ting Xue/
DATE SIGNED:	06/04/2020
Total Attachments: 3	
source=AssignDecl002830008#page1.tif	
source=AssignDecl002830008#page2.tif	
source=AssignDecl002830008#page3.tif	

COMBINED DECLARATION AND ASSIGNMENT

DECLARATION

As the below named inventors, I hereby declare that:

This declaration is directed to:

- The attached application, or
- United States application or PCT international application number _____
filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the below named inventors, each of the below named inventors, hereby sell and assign to **Yangtze Memory Technologies Co., Ltd.**, a corporation formed under the laws of China, whose mailing address is 18 Gaoxin 4th Road, East Lake High-Tech Development Zone, Wuhan, Hubei, China (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

(a) in the invention(s) known as **HYBRID WAFER BONDING METHOD AND STRUCTURE THEREOF** for which application(s) for patent in the United States of America is identified above, in any and all applications thereon, in any and all Letters Patent(s) therefor, and

(b) in any and all applications that claim the benefit of the patent application identified above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above in part (a), to the full extent of the term or terms for which Letters Patents issue, and

(c) in any and all inventions described in the patent application identified above in part (a), and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The below named inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

The below named inventors agree to execute all papers necessary in connection with any patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such patent enforcement action.

The below named inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The below named inventors hereby represent that he/she understands that the patent practitioners associated with **CUSTOMER NUMBER 165026** are the legal representatives of, and attorneys for, the assignee, and are NOT the legal representatives of, and attorneys for, the inventors.

IN WITNESS WHEREOF, executed by the below named inventors on the date opposite his/her name.

LEGAL NAME OF INVENTOR

Inventor: Meng YAN Date: 2020, 4, 16

Signature of Inventor: Meng Yan Meng YAN